**Product End-of-Life Disassembly Instructions**

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**
[List multiple models if applicable.]

*HP ENVY x2 Detachable PC 12*

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm MB / USB DB / IR+ALS DB / TS DB</td>
<td>4</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries  Main battery</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps  12.3&quot;</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Power cord</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at [EL-MF877-01](#)
Components, parts and materials containing refractory ceramic fibers

Components, parts and materials containing radioactive substances

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 Screw driver</td>
<td>#1 / #0</td>
</tr>
<tr>
<td>Description #2 Heat gun</td>
<td></td>
</tr>
<tr>
<td>Description #3 Suction cup</td>
<td></td>
</tr>
<tr>
<td>Description #4 Opening stick</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Disassemble LCD
2. Remove LCD cable and TS cable
3. Remove the SD Card Tray
4. Remove the Nano SIM Card Tray
5. Remove TS M/B
6. Remove Slate frame left
7. Remove 1 pcs of screws and disassemble Slate frame FPC
8. Remove 1 pcs of screws and disassemble Slate frame right
9. Remove 2 pcs of screws and disassemble USB-C MB CONN BKT
10. Remove TS FPC
11. Remove 3 pcs of screws and disassemble Battery CONN BKT
12. Remove 4 pcs of screws and disassemble Battery
13. Remove 2 pcs of screws and disassemble Slate Frame down.
14. Remove 1 pcs of screws and disassemble USB C SUP BKT
15. Remove 1 pcs of LED LENS RUBBER
16. Remove USB FPC
17. Remove USB M/B
18. Remove LCD FPC.
19. Remove 2 pcs of screws and Gasket Mylar, disassemble Pogo Pin FPC.
20. Remove 1 pcs of screws and disassemble Audio FPC
21. Remove 1 pcs of screws and disassemble Volume FPC
22. Loose Antenna deduction point on M/B
23. Remove the Rear Camera, Front camera, WEB CAM LED FPC, IR Camera.
24. Remove the IR FPC
25. Remove the IR M/B
26. Remove 2 pcs of screws and disassemble SPK L side.
27. Remove 2 pcs of screws and disassemble PW FPC
29. Remove 4 pcs of screws and disassemble M/B
30. Remove Camera Frame
31. Disassemble Front MIC FPC

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

PSG instructions for this template are available at EL-MF877-01
3.21 Total part disassembly

3.22 Disassemble LCD and remove LCD cable and TS cable

3.23 Remove the SD Card Tray

3.24 Remove the Nano SIM Card Tray

3.25 Remove TS M/B

3.26 Remove Slate frame left
3.27 Remove 1 pcs of screws and disassemble Slate frame FPC

3.28 Remove 1 pcs of screws and disassemble Slate frame right

3.29 Remove 2 pcs of screws and disassemble USB-C MB CONN BKT

3.30 Remove TS FPC

3.31 Remove 3 pcs of screws and disassemble Battery CONN BKT

3.32 Remove 4 pcs of screws and disassemble Battery

3.33 Remove 2 pcs of screws and disassemble Slate Frame down
3.34 Remove 1 pcs of screws and disassemble USB C SUP BKT

3.35 Remove 1 pcs of LED LENS RUBBER

3.36 Remove USB FPC

3.37 Remove USB M/B
3.38 Remove LCD FPC

3.39 Remove 2 pcs of screws and Gasket Mylar, disassemble Pogo Pin FPC.

3.40 Remove 1 pcs of screws and disassemble Audio FPC

3.41 Remove 1 pcs of screws and disassemble Volume FPC
3.42 Remove the Rear camera, Front camera, WEB CAM LED FPC, IR Camera

3.43 Remove the IR FPC

3.44 Remove the IR M/B

3.45 Remove 2 pcs of screws and disassemble SPK L side
3.46 Remove 2 pcs of screws and disassemble PW FPC

3.47 Disassemble SPK R side

3.48 Remove 4 pcs of screws and disassemble M/B

3.49 Remove Camera Frame
3.50 Disassemble Front MIC FPC